

# SMB1N-430H-02

- Blue High Power LED
- 430 nm, 500 mW
- SMD package, PA9T
- Dimension: 5.0 x 5.2 x 5.5 mm
- Viewing Angle: 22°

### Description





Rev. 1.3, 19.12.2018

**SMB1N-430H-02** is a surface mount InGaN High Power LED with a typical peak wavelength of **430 nm** and radiation of **500mW**. It comes in SMD package (PA9T) with silver plated soldering pads (lead free solderable), copper heat sink, and molded with silicone resin.

### Maximum Ratings (T<sub>CASE</sub>=25°C)

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Parameter	Symbol	Min.	Max.	Unit	
Power Dissipation	PD		1900	mW	
Forward Current	IF		500	mA	
Pulse Forward Current *1	IFP		1000	mA	
Reverse Voltage	VF		5	V	
Thermal Resistance	Rthja		10	K/W	
Junction Temperature	$T_J$		120	°C	
Operating Temperature	TCASE	- 40	+ 100	°C	
Storage Temperature	Tstg	- 40	+ 100	°C	
Lead Solder Temperature *2	T <sub>SLD</sub>		+ 250	°C	

\*1 duty=1%, pulse width = 10  $\mu$ s

\*2 must be completed within 5 seconds

# Electro-Optical Characteristics (TCASE=25°C)

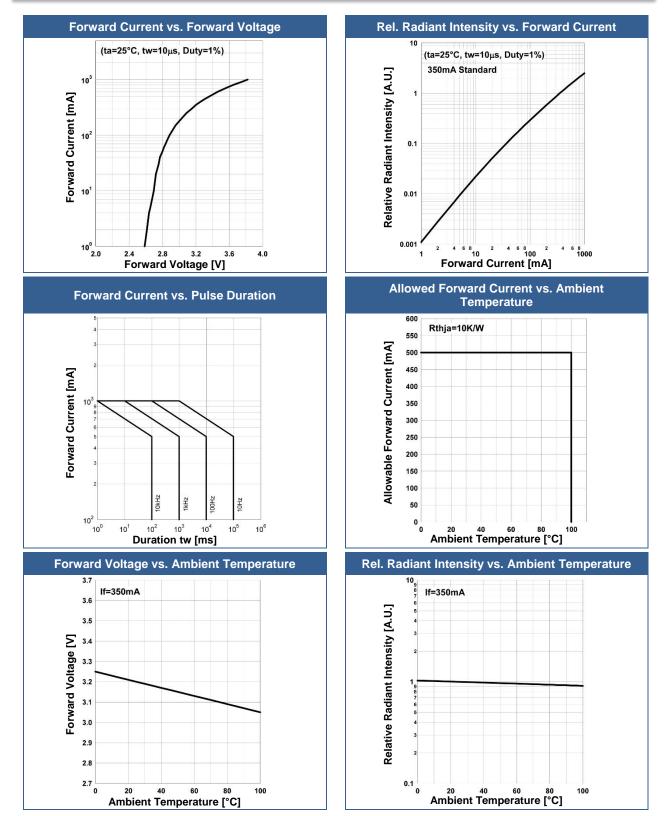
Parameter	Symbol	Conditions	Min.	Values Typ.	Max.	Unit
Peak Wavelength	$\lambda_P$	I <sub>F</sub> =350mA	420		440	nm
Dominant Wavelength	$\lambda_D$	I⊧=350mA		438		nm
Half Width	$\Delta \lambda$	I <sub>F</sub> =350mA		15		nm
Forward Voltage	VF	I <sub>F</sub> =350mA		3.2	3.8	V
	V <sub>FP</sub>	IFP=1A		3.8		
Radiated Power *1	л	I <sub>F</sub> =350mA		500		mW
	Po	IFP=1A		1200		
Radiant Intensity *2	,	I <sub>F</sub> =350mA		1400		mW/sr
	IE	IFP=1A		3500		
Luminous Flux	$I_V$	I <sub>F</sub> =350mA		5.5		Im
Viewing Angle	φ	I <sub>F</sub> =100mA		22		deg.
Rise Time	t <sub>R</sub>	I <sub>F</sub> =350mA		30		ns
Fall Time	t⊨	I <sub>F</sub> =350mA		50		ns

\*1 measured by S3584-08

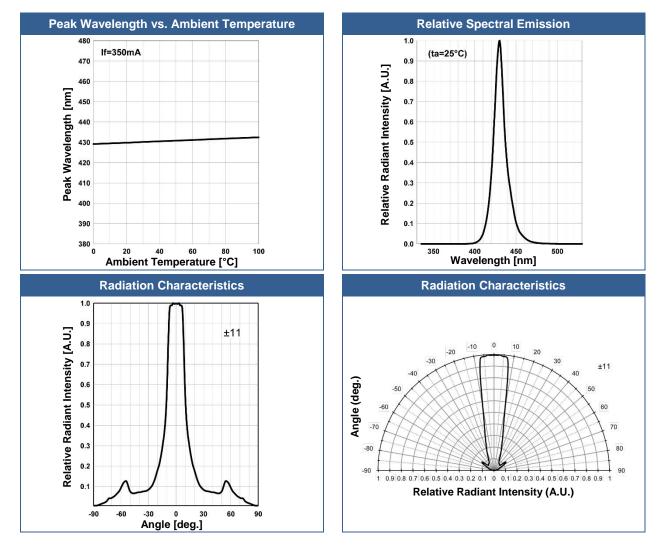
\*2 measured by CIE127-2007 Condition B



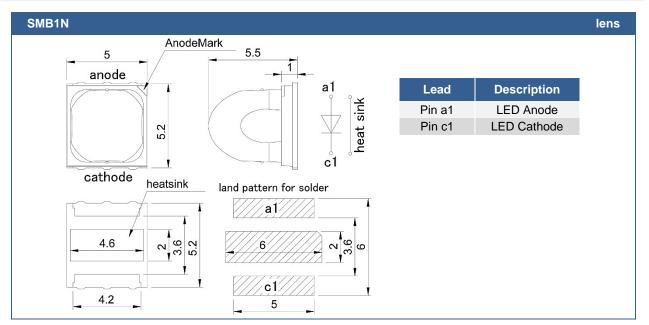
# **Typical Performance Curves**







## **Outline Dimensions**



All Dimensions in mm



### Precautions

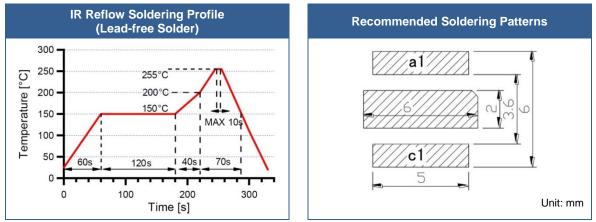
#### Soldering:

- Do avoid overheating of the LED
- Do avoid electrostatic discharge (ESD)
- Do avoid mechanical stress, shock, and vibration
- Do only use non-corrosive flux
- Do not apply current to the LED until it has cooled down to room temperature after soldering

#### **Recommended soldering conditions:**

This LED is designed to be reflow soldered on to a PCB. If dip soldered or hand soldered, its reliability cannot be guarantee.

Nitrogen reflow soldering is recommended. Air flow soldering conditions can cause optical degradation, caused by heat and/or atmosphere.



Above table specifies the maximum allowed duration and temperature during soldering. It is strongly advised to perform soldering at the shortest time and lowest temperature possible.

#### **Cleaning:**

#### Cleaning with isopropyl alcohol, propanol, or ethyl alcohol is recommended

DO NOT USE acetone, chloroseen, trichloroethylene, or MKS DO NOT USE ultrasonic cleaners

#### **Static Electricity:**

**LEDs are sensitive to electrostatic discharge (ESD)**. Precautions against ESD must be taken when handling or operating these LEDs. Surge voltage or electrostatic discharge can result in complete failure of the device.

#### **Radiation:**

During operation these LEDs do emit **high intensity light**, which is hazardous to skin and eyes, and may cause cancer. Do avoid exposure to the emitted light. **Protective glasses are recommended**. It is further advised to attach a warning label on products/systems.

#### **Operation:**

#### Do only operate LEDs with a current source.

Running these LEDs from a voltage source will result in complete failure of the device. Current of a LED is an exponential function of the voltage across it. Usage of current regulated drive circuits is mandatory.

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